

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Mallinckrodt Inc.	01/28/2008

RECEIVING PARTY DATA

Name:	Mallinckrodt Baker, Inc.
Street Address:	222 Red School Lane
City:	Phillipsburg
State/Country:	NEW JERSEY
Postal Code:	08865

PROPERTY NUMBERS Total: 4

Property Type	Number
Patent Number:	6899818
Patent Number:	6465403
Patent Number:	6585825
Patent Number:	6599370

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:

1484 & 1162 US ASG BAKER

NAME OF SUBMITTER:

Christine R. Cooke

Total Attachments: 4

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PATENT ASSIGNMENT AGREEMENT

This Patent Assignment Agreement is between, Mallinckrodt Inc., a Delaware corporation, having a place of business at 675 McDonnell Blvd., Hazelwood, Missouri 63042 ("Mallinckrodt") and Mallinckrodt Baker, Inc., a New Jersey corporation, having a place of business at 222 Red School Lane, Phillipsburg, New Jersey 08865 ("MBI"), and is effective January 28, 2008 ("Effective Date"). Mallinckrodt and MBI are herein referred to collectively as the "Parties".

WHEREAS, Mallinckrodt is the record title holder of the patents and patent applications listed in Exhibit A and the inventions disclosed and claimed therein (hereinafter referred to as the "Patent Rights");

WHEREAS, Mallinckrodt and MBI have been related companies under common ownership such that Mallinckrodt has been record title holder to the Patent Rights and whereas for U.S. income tax purposes MBI is the beneficial owner of the Patent Rights;

WHEREAS, Mallinckrodt and MBI have been part of a single business entity, and therefore it has been convenient that Mallinckrodt hold record title to the Patent Rights;

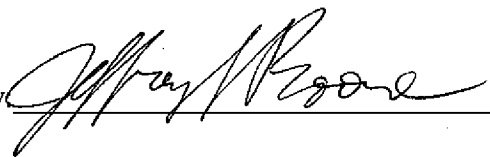
WHEREAS, it is now contemplated that Mallinckrodt and MBI will become members of different business entities, and it therefore will become convenient to merge record title of the Patent Rights into the beneficial ownership of MBI;

NOW, THEREFORE, in consideration of the foregoing, and for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, Mallinckrodt, intending to be legally bound, hereby assigns all its right, title and interest in the Patent Rights to MBI to have and hold as if it had originally been granted the Patent Rights, including, without limitation, its title in the patents and patent applications listed in Exhibit A, and further agrees, whenever reasonably called upon to do so by MBI, to attest (at MBI's expense) to MBI's right to the Patent Rights, and to any rights derivative from the Patent Rights, such as the right to file for further patent rights relating to the Patent Rights and the right to receive damages or other compensation for any past infringement of the Patent Rights. MBI hereby accepts said assignment.

IN WITNESS WHEREOF, the Parties hereto have caused this Patent Assignment Agreement to be duly executed as of the Effective Date.

MALLINCKRODT INC.

MALLINCKRODT BAKER, INC.

By: 

By: 

Date: 2008 Jan 28

Date: Jan 28, 2008

Jeffrey S. Boone
Vice President

Christine R. Cooke
Assistant Secretary

EXHIBIT A

Patent Rights

Appln. No.	Patent No.	Appln. Status	Country	Filing Date	Issue Date	Title
	6,899,818	Granted	United States	04-Sep-2002	31-May-2005	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
US.P 6899818		Abandoned	United States	20-Mar-2000		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
WO US01/08772		Converted	PCT	19-Mar-2001		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
CA 2403730	CN 239304	Pending	Canada	19-Mar-2001		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
EP 01918830.9		Granted	China	19-Mar-2001	07-Dec-2005	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	IL 151792	Pending	Europe	19-Mar-2001		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
		Granted	Israel	19-Mar-2001	06-Oct-2006	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
JP 2001-569560		Pending	Japan	19-Mar-2001		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
KR 10-2002-7012303		Pending	Korea	19-Mar-2001		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	MY 129673-A	Granted	Malaysia	08-Feb-2001	30-Apr-2007	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	NZ 522079	Granted	New Zealand	19-Mar-2001	07-Oct-2004	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	PL 195792	Granted	Poland	19-Mar-2001	19-Mar-2007	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	SG 92040	Granted	Singapore	19-Mar-2001	30-Sep-2004	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
TH 064318		Pending	Thailand	16-Mar-2001		Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	TW I239435	Granted	Taiwan	21-Feb-2001	11-Sep-2005	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates
	6,465,403	Granted	United States	17-Nov-2000	Oct. 15, 2002	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	6,585,825	Granted	United States	16-Oct-2000	July 1, 2003	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	6,599,370	Granted	United States	16-May-2001	July 29, 2003	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
US.P 60/085861		Abandoned	United States	18-May-1998		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
US.P 60/115084		Abandoned	United States	07-Jan-1999		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
WO US99/10875		Converted	PCT	17-May-1999		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates

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Appln. No.	Patent No.	Appln. Status	Country	Filing Date	Issue Date	Title
WO US01/42406		Converted	PCT	28-Sep-2001		Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	BE 1326951	Granted	Belgium	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
CA 2330747		Pending	Canada	17-May-1999		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
CA 2425613		Pending	Canada	28-Sep-2001		Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
CN 99808801.3		Pending	China	17-May-1999	12-Oct-2007	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	CN ZL01817467.1	Granted	China	28-Sep-2001	08-Jun-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	DE 60108774.7	Granted	Germany	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
EP 99925649.8		Pending	Europe	17-May-1999		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	EP 1326951	Converted	Europe	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	FR 1326951	Granted	France	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	GB 1326951	Granted	United Kingdom	28-Sep-2001	05-Feb-2005	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
HK 02101291.2		Pending	Hong Kong	17-May-1999		Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	HK 1062310	Granted	Hong Kong	28-Sep-2001	08-Jun-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	IE 1326951	Granted	Ireland	28-Sep-2001	05-Feb-2005	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	IL 139546	Granted	Israel	17-May-1999	01-Dec-2005	Microelectronic Substrates
	IL 155429	Granted	Israel	28-Sep-2001	22-May-2006	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	IN 206990	Granted	India	28-Sep-2001	16-May-2007	Microelectronic Substrates
	IT 1326951	Granted	Italy	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
JP 2000-550003		Pending	Japan	17-May-1999		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
JP 2002-536403		Pending	Japan	28-Sep-2001		Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	KR 10-0610387	Granted	South Korea	17-Nov-2000	01-Aug-2006	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
KR 2003-7005353		Pending	South Korea	28-Sep-2001		Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
MX PA/a/2000/011391		Pending	Mexico	17-Nov-2000		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates

Appln. No.	Patent No.	Appln. Status	Country	Filing Date	Issue Date	Title
	MX 234381	Granted	Mexico	28-Sep-2001	13-Feb-2006	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	MY 121446	Granted	Malaysia	18-May-1999	28-Jan-2006	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	MY 124511	Granted	Malaysia	04-Oct-2001	30-Jun-2006	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	NL 1326951	Granted	Netherlands	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	SE 1326951	Granted	Sweden	28-Sep-2001	05-Feb-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	SG 76944	Granted	Singapore	17-May-1999	30-Jun-2004	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	SG 95800	Granted	Singapore	28-Sep-2001	29-Jul-2005	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
TH 050487		Pending	Thailand	17-May-1999		Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
	TH 21687	Granted	Thailand	12-Oct-2001	03-Apr-2007	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates
	TW 1226520	Granted	Taiwan	18-May-1999	05-Nov-2004	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates
TW 90125230		Pending	Taiwan	12-Oct-2001		Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates